

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJND2004
Package Type :	DFNWB5x2-6L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.2428%
Lead Frame	Cu	7440-50-8	97.40%	57.4261%
	Fe	7439-89-6	2.40%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.10%	
	Ag	7440-22-4	0.02%	
Epoxy	Silver	7440-22-4	71.00%	0.2833%
	Epoxy resin	proprietary	18.00%	
	Epoxy resin modier	proprietary	7.00%	
	dapsone	80-08-0	3.00%	
	substituted silane	proprietary	1.00%	
Wire1	Cu	7440-50-8	97.00%	0.0809%
	Pd	7440/5/3	3.00%	
Wire2	Cu	7440-50-8	97.90%	0.2428%
	Pd	7440-05-3	1.98%	
	Au	7440-57-5	0.12%	
Mold Compound	Epoxy resin A	Trade Secret	3.00%	39.741%
	Epoxy resin B	Trade Secret	2.00%	
	Phenol Resin A	Trade Secret	4.00%	
	Phenol Resin B	Trade Secret	2.00%	
	Silica(Amorphous) A	Trade Secret	84.00%	
	Carbon black	7631-86-9	3.00%	
	Metal Hydroxide	Trade Secret	2.00%	
Plating	Tin	7440-31-5	100.00%	1.983%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.